

IN THE SPECIFICATION:

Replace the paragraph at column 1, lines 5-10, with the following new paragraph:

B6
--The present invention relates generally to memory media and I/O device containers, and more particularly to a packaging container for printed circuit boards that conforms to standards set by PCMCIA JEIDA [JEDIC], ISO, etc. for peripheral devices.

Replace the paragraph at column 1, lines 50-55, with the following new paragraph:

B7
--Accordingly, it is an object of the present invention to provide a PCMCIA style peripheral device container that meets PCMCIA, JEIDA [JEDIC], and ISO standards. It is a further object of the present invention to provide a container that comprises few components to reduce manufacturing cost.

Replace the paragraph at column 2, lines 57-63, with the following new paragraph:

B8
--The present invention is a PCMCIA style peripheral device package 10. Referring to FIG. 1 it can be seen that the package 10 comprises chiefly an upper cover or first package half 12, a lower cover or second package half 14, an upper frame element 16, and a lower frame element 18. The covers 12 & 14 are formed from stamped metal, and the frame elements 16 & 18 are molded plastic.

Replace the paragraph at column 3, lines 25-36, with the following new paragraph:

B9
--In order to facilitate bonding, the edges of the covers 12 & 14 are bent to conform to the shape of the frame elements 16 & 18. As shown in FIG. 4, the edges of the covers 12 and 14 have a generally u-shaped configuration. In addition, metal fingers 26 are provided on each side of the covers 12 & 14. The metal fingers 26 become embedded in the